

U.S. Department of Commerce, Patent and Trademark	Atty. Docket No.	Application No.
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	SENS.007US1	10/619,731
(Use several sheets if necessary)	Applicant(s)	Conf. No.
(Form PTO-1449)	Wayne Glenn RENKEN	7022
	Filing Date	Art Group
	July 15, 2003	1763

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>R</i>	1	4,685,331	08-1987	RENKEN et al.			
<i>R</i>	2	5,670,218	09-1997	BAEK			
<i>R</i>	3	6,494,955	12-2002	LEI et al.			

U.S. Published Patent Application Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate

Foreign Patent Documents

							Translation	
		Document	Date	Country	Class	Subclass	Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>R</i>	4	Smith et al., "Modeling the impact of thermal history during post exposure bake on the lithographic performance of chemically amplified resists", Proceeding of the SPIE, Vol. 4345, pp. 1013-1021 (2001), Advances in Resist Technology and Processing XVIII.					

Examiner

Date Considered

12/16/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP-609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.